



Material Content Data Sheet



Sales Product Name		1ED020I12-F2		Issued		24. January 2018		
MA#		MA001692522						
Package		PG-DSO-16-15		Weight*		449.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.549	1.01	1.01	10127	10127
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		70	
	non noble metal	zinc	7440-66-6	0.126	0.03		281	
	non noble metal	iron	7439-89-6	2.521	0.56		5613	
wire	non noble metal	copper	7440-50-8	102.369	22.79	23.39	227922	233886
	noble metal	gold	7440-57-5	0.646	0.14	0.14	1438	1438
	encapsulation	organic material	carbon black	1333-86-4	1.664	0.37		3706
encapsulation	plastics	epoxy resin	-	44.938	10.01		100054	
	inorganic material	silicondioxide	60676-86-0	286.274	63.73	74.11	637385	741145
	leadfinish	non noble metal	tin	7440-31-5	2.873	0.64	0.64	6397
plating	noble metal	silver	7440-22-4	1.017	0.23	0.23	2264	2264
glue	plastics	epoxy resin	-	0.533	0.12		1186	
	noble metal	silver	7440-22-4	1.598	0.36	0.48	3557	4743
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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